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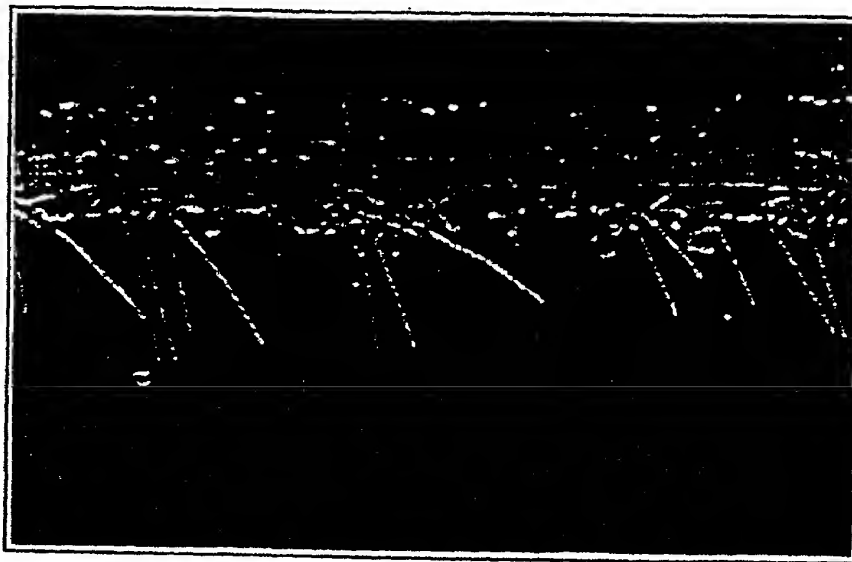
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(54) Title: A METHOD OF PROCESSING A POLYMER LAYER



← Wafer edge

Edge cracking as seen by optical microscope under dark field illumination

(57) Abstract

This invention relates to a method of processing polymer layers, for example low dielectric constant films, and includes the steps of heating the layer to desorb moisture and harden the layer and exposing the layer to a plasma during the heating process.